

Application No.: 10/033,749

Docket NO.: JCLA8479

**Amendment****FOR THE CLAIMS:**

Claim 1. (Currently amended) A resilient and rugged probe, to measure an on-wafer signal, the probe comprising:

a metal probe tip;

a resilient multi-layered dielectric substrate;

a planar transmission structure, coupled to the metal probe tip and attached onto the resilient multi-layered dielectric substrate, wherein the metal probe tip extends out from the planar transmission structure without being attached to the resilient multi-layered dielectric substrate; and

a fixed end, coupled to the resilient multi-layered dielectric substrate and the planar transmission structure, wherein the fixed end is used as a transmission structure converter of the probe to connect the planar transmission structure to a coaxial transmission structure.

Claim 2. (Previously cancelled).

Claim 3. (Original) The resilient and rugged probe according to claim 1, wherein the metal probe tip is used to probe the on-wafer signal.

Claim 4. (Currently cancelled).

Claim 5. (Previously amended) The resilient and rugged probe according to claim 1, wherein the metal probe tip is able to lift and dive with a second angle.

Claim 6. (Original) The resilient and rugged probe according to claim 1, wherein the fixed end is used to support and hold the probe.

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**Claims 7-11 and 13-15. (Currently cancelled).**

**Claim 12 and 16-23. (Previously cancelled).**